

**IN THE SPECIFICATION**

On page 1, after the Title, insert:

**--Cross-Reference To Related Applications**

This application is a continuation of U.S. Application Serial No. 10/342,955 filed January 15, 2003, which is a divisional of U.S. Application Serial No. 09/210,517 filed December 11, 1998, now issued as U.S. Patent No. 6,523,736 on February 25, 2003.--

**IN THE CLAIMS**

Please cancel claims 1-34 and 36-53 without prejudice.

Please amend claim 35 as set forth below:

35. (Once Amended) A method of forming solder balls, the method comprising the acts of:

- (a) ~~providing a stencil disposed on a substrate, the stencil having a plurality of holes therein;~~
- (b) ~~disposing solder within thea plurality of holesreceptacles disposed within a surface of a conveyor belt; and~~
- (eb) ~~heating the solder disposed within the holes of the stencil disposed on the substratereceptacles to form a solder ball within each holereceptacle.~~

Please add claims 54-61 as set forth below:

54. The method as recited in claim 35, wherein disposing solder within the plurality of receptacles comprises disposing solder within the plurality of receptacles formed by a first portion of the conveyor belt having a plurality of holes disposed upon a second portion of the conveyor belt.